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Related WPI Acc No: 1998-428196; 2001-160394; 2001-191964; 2001-211675;
  2001-227246; 2001-282398; 2001-308928; 2001-336246; 2001-344491;
  2001-344493; 2001-344496; 2001-356614; 2001-356615; 2001-356619;
  2001-356628; 2001-375368; 2001-379603; 2001-382156; 2001-382157;
  2001-398732; 2001-398749; 2001-406342; 2001-433210; 2001-433216
XRAM Acc No: C01-134281
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 Polyorganosiloxane-based composition for forming film comprises two
 products obtained by hydrolyzing and condensing silane compound in
 presence of acid and alkali catalysts respectively
Patent Assignee: JSR CORP (JAPS )
Inventor: HAYASHI E; KONNO K; KUROSAWA T; SHIOTA A; YAMADA K; YOUNGSOON
Number of Countries: 029 Number of Patents: 005
Patent Family:
Patent No
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               A2 20010411 EP 2000121101
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Priority Applications (No Type Date): JP 99275553 A 19990929
Patent Details:
Patent No Kind Lan Pg
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EP 1090967
              A2 E 15 C09D-183/04
   Designated States (Regional): AL AT BE CH CY DE DK ES FI FR GB GR IE
IT
   LI LT LU LV MC MK NL PT RO SE SI
JP 2001164186 A
                    14 C09D-183/04
KR -2001077882--A---
                       C08L-083/04
US 6410150.
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                       B32B-009/04
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Abstract (Basic): EP 1090967 A2
        NOVELTY - A composition comprises a product of hydrolysis and
    condensation obtained by hydrolyzing and condensing at least one
silane
    compound, in the presence of an alkali catalyst and a product of
    hydrolysis and condensation obtained by hydrolyzing and condensing
at
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least one silane compound in the presence of an acid catalyst.

DETAILED DESCRIPTION - A composition comprises (a) a product

obtained by hydrolyzing and condensing at least one silane compound of formula RaSi(OR1)4-a (I), Si(OR2)4 (II) or R3b(R4O)3-bSi-(R7)d-Si(OR5)3-cR6c (III) in the presence of an catalyst and (b) a product obtained by hydrolyzing and condensing (I), (II) or (III) in the presence of an acid catalyst. R=H, fluorine or monovalent organic group; R1 - R6=monovalent organic group; R7=0, phenylene or -(CH2)n-;n=1 - 6;a=1 or 2; b and c=0 - 2; and d=0 or 1. INDEPENDENT CLAIMS are also included for the following: (A) forming a film by applying the composition on a substrate and then heating the composition; and (B) a semiconductor device having the insulating film. USE - For forming film, preferably insulating film (claimed), used as coating film for semiconductor devices such as LSIs, system LSIs, DRAMs, SDRAMs, RDRAMs and D-RDRAMs; protective films such as coat films for semiconductor devices; interlayer insulating films for multilayered printed circuit boards; and protective or insulating films for liquid-crystal display devices. Also, useful in application in which the composition is applied to silicon wafer, SiO2 wafer, SiN wafer, glasses, ceramics and metals. ADVANTAGE - The film has a low dielectric constant, high modulus of elasticity, low water absorption, good storage stability and low film density. pp; 15 DwgNo 0/0 Technology Focus: TECHNOLOGY FOCUS - ORGANIC CHEMISTRY - Preferred Composition: A weight average molecular weight as determined by GPC (refractive viscosity or light scattering) of component (a) is 50,000 -10,000,000 and of component (b) is 500 - 300,000. Component (a) contains a of hydrolysis of condensation of (II) (5 - 75 wt.%) (in terms of the product of complete hydrolysis and condensation). Component (a) is the product of hydrolysis and condensation of (I) and (II). The composition comprises (parts by weight) component (a) (100) and component (b)

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900) (in terms of the product of complete hydrolysis and
 condensation)
     and has a pH of at most 7.
 Title Terms: BASED; COMPOSITION; FORMING; FILM; COMPRISE; TWO; PRODUCT;
   OBTAIN; CONDENSATION; SILANE; COMPOUND; PRESENCE; ACID; ALKALI;
 CATALYST:
   RESPECTIVE
 Derwent Class: A26; A85; G02; L03; P73; U11
 International Patent Class (Main): B32B-009/04; C08L-083/04; C09D-
 183/04
 International Patent Class (Additional): C08G-077/08; C09D-183/02;
   C09D-183/14; H01L-021/312
 File Segment: CPI; EPI; EngPI
 Manual Codes (CPI/A-N): A06-A00E1; A06-A00E2; A07-A03; A12-B01C; A12-
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